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FOR IMMEDIATE RELEASE

Press Release

YINCAE to Showcase Innovative Products at Wafer-Level Packaging Symposium

(Albany, NY) 12/30/2025 — YINCAE Advanced Materials, a leading supplier of high-performance materials for advanced semiconductor packaging, will showcase its latest wafer-level packaging solutions at the **Wafer-Level Packaging Symposium**, taking place **February 17–19, 2026, in San Francisco, California, USA**.

At the event, YINCAE will highlight **TM 150LM liquid metal thermal interface material** in combination with **LA 150 rubber sealant**, a material system designed to deliver **low thermal impedance while significantly reducing mechanical stress on chips**. This solution is well suited for wafer-level and advanced packaging applications requiring both thermal efficiency and mechanical compliance. **TM 150LM** with **LA 150** has successfully passed **five reflow cycles at 260 °C with no observable change in material performance**, demonstrating excellent thermal and mechanical reliability.

YINCAE will also feature **UF 66L**, an **optical-grade underfill developed for silicon photonics applications**. UF 66L provides high optical clarity, stable mechanical properties, and robust reflow reliability. The material has passed **five reflow cycles at 260 °C without any performance degradation**, meeting the stringent requirements of silicon photonics and optoelectronic packaging.

“These materials reflect YINCAE’s continued focus on enabling advanced wafer-level and photonics packaging with proven reliability,” said Dr. Wusheng Yin, CTO at YINCAE. “Our solutions are designed to support customers addressing thermal management, stress reduction, and high-temperature assembly challenges.”

YINCAE invites conference attendees to visit the YINCAE Booth to learn more about its wafer-level packaging materials and to discuss application-specific solutions.

For more information on **TM 150LM**, **UF 66L**, **or YINCAE’s full product portfolio**, please contact info@yincae.com or visit www.yincae.com

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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